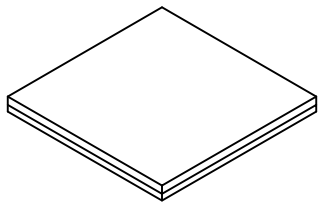
HMCCA,01/24/00,10:30:15,PBGAL20101,jd-01 GREME,09/05/00,16:34:04,MP517Q

REVISION HISTORY					
REV	DCN NUMBER	DESCRIPTION	ORIGINATOR	INCORPORATOR	DATE
00	C05652	INITIAL RELEASE	LMACK	LMACK	03/12/99
01	C10059	ADDED 289 BALL MATRIX	GREME	LMACK	09/29/00
02	L81042	CHANGE MOLD CAP TO 0.70mm ON SHT1	ZTUSI	ZTUSI	11/13/00



7. REFERENCE SPECIFICATIONS:
   A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AAWW SPEC #001-0519-2062: MARKING.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 289.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 17 X 17.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.80mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
DECIMAL X.X ±0.1, X.XX ±0.05, X.XXX ±0.030
ANGULAR ±1°
INTERPRET DIM AND TOL PER ASME Y14.5M - 1994
MATERIAL: N/A
FINISH: N/A
DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION

APPROVALS	DATE
DESIGNED: LMACK	02/26/99
CHECKED: JMICK	02/26/99
PRODUCT MANAGER: TPANC	02/26/99
RELEASED: GSCHU	03/12/99

Amkor Technology, Inc.
Chandler, Arizona, USA
Anam Semiconductor, Inc.,
Seoul, Korea
Amkor Technology Philippines, Inc.
Manila, Philippines

Amkor Technology / ANAM Semiconductor

TITLE: PACKAGE OUTLINE - MAF, 17 X 17 MATRIX, 15.00mm X 15.00mm X 1.60mm, 0.70mm MOLD CAP, 0.46mm BALL, 0.80mm PITCH, LAMINATE SUBSTRATE, AWW

SIZE	SID NUMBER	DWG NUMBER	REV
A3	N/A	75149	02

STRIP DWG NUMBER/REV	PKG OUTLINE DWG NO.	SCALE	SHEET
N/A	N/A	NONE	1 OF 3

FORM NO: MBPLAN1C1.DWG